

ABSTRACT

5 A method is provided for manufacturing a housing
(10) for containing an IC card (12). The method includes
the steps of stamping a pair of metal covers (16,20) with
at least one of the covers having a continuous
uninterrupted edge (32) provided with a plurality of
through holes (34) spaced inwardly of and along the edge.
The covers (16,20) are placed into a mold for an injection
molding process. Plastic support members (18,24) are
10 injected into the mold into attachment with the covers.
Plastic material of the support member surrounds the edge
(32) and flows through the holes (34) of the cover. The
covers (16,20) and attached support members (18,24) are
removed from the mold, and the support members are bonded
15 together so that a housing (10) is formed with the covers
and within which the IC card (12) can be contained.

